

Page 3, between lines 10 and 12, insert

-- Summary of the Invention: --;

Page 11, before line 1, insert

-- Brief Description of the Drawing:

Fig. 1 shows a cross sectional view of the layers  
of a component.

Description of the Preferred Embodiment: --.

Page 17, top, change "Patent claims" to -- We Claim: --.

Page 18, top, change "Abstract" to -- Abstract of the

Disclosure: --; and

Page 18, line 9, delete the paragraph reading, "FIG 1".

In the Claims:

Cancel claims 1-3 and enter the following new claims.

-- 4. A process for metallizing at least one insulating layer  
of an electronic or microelectronic component, which comprises:

applying at least one first insulating layer to a substrate such  
that the first insulating layer has a thickness not greater than

50 $\mu$ m;